EMC Components

RF Chokes High Current
B82432-H



SIMID 03 (Siemens Miniature Inductors) Rated inductance 1,0 bis 330 μ H Rated current 0.11 to 1,10 A

Construction

- Size as per EIA standard: 1812
- Ferrite core
- Winding US- welded, flame- retardant encapsulation
- Temperature index of wire enamel: ≥180 °C

Features

- Very high current handling capability
- High Q factor
- High resonance frequency
- Suitable for reflow (IR and vapor phase) and wave soldering
- Different measuring frequencies for L and Q

Applications

- Filtering of supply voltages, coupling, decoupling
- Antenna systems
- Automotive electronics
- Telecommunications

Terminals

- Silver- plated
- Base material: CuSn6, 1–2 μm Cu, 4–6 μm Ag
- Suitable for soldering and conductive adhesion
- No leaching during wave soldering

Marking

Marking on component:

Manufacturer, "H" (high- current version)

L value (in nH) and tolerance of L value (coded),
date of manufacture (coded)

Minimum marking on reel:

Manufacturer, part number, ordering code, L value and tolerance of L value, quantity, date of packing

Delivery mode

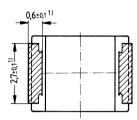
12- mm blister tape wound on 330- mm Ø reel For details on taping, packing and packing units see data book "EMC components", page 433.

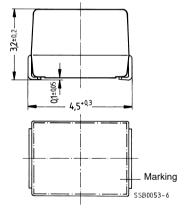


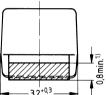


Dimensional drawing

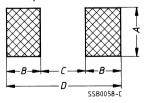
EIA size 1812, approx. weight 130 mg







PCB layout recommendation



Dimensions (mm)	Α	В	С	D
Wave soldering	3,1	1,7	3,2	6,6
Reflow soldering	3,6	1,3	3,2	5,8

¹⁾ Soldering area, silver- plated



Characteristics and ordering codes

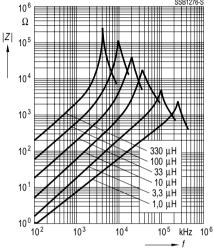
For further technical data see page 7

<i>L</i> _R ¹⁾ μΗ	Toler- ance	f _L MHz	Q _{min}	f _Q MHz	I _R mA	$R_{max} \ \Omega$	f _{res, min} MHz	Ordering code
1,0	± 10 %	1	20	7,96	1100	0,11	260	B82432- H1102- K
1,5	≟K	1	20	7,96	1000	0,14	175	B82432- H1152- K
2,2		1	20	7,96	900	0,18	95	B82432- H1222- K
3,3		1	20	7,96	820	0,22	80	B82432- H1332- K
4,7		1	20	7,96	740	0,27	40	B82432- H1472- K
6,8		1	20	7,96	660	0,35	36	B82432- H1682- K
10		1	25	2,52	600	0,50	25	B82432- H1103- K
15		0,1	25	2,52	480	0,70	20	B82432- H1153- K
22		0,1	25	2,52	430	0,90	18	B82432- H1223- K
33		0,1	25	2,52	350	1,4	15	B82432- H1333- K
47		0,1	25	2,52	310	1,9	11,5	B82432- H1473- K
68		0,1	25	2,52	230	2,6	10,0	B82432- H1683- K
100		0,1	25	0,796	180	4,0	8,0	B82432- H1104- K
150		0,1	25	0,796	150	6,1	6,5	B82432- H1154- K
220		0,1	25	0,796	130	7,5	4,5	B82432- H1224- K
330		0,1	25	0,796	110	11,0	3,5	B82432- H1334- K

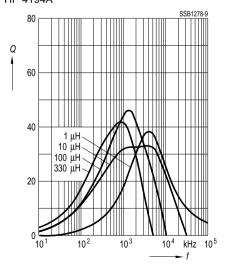
¹⁾ Additional ratings E 12 upon request



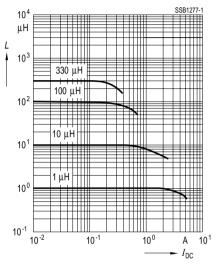
Impedance |Z| versus frequency f measured with impedance analyzer HP 4191A / HP 4194A



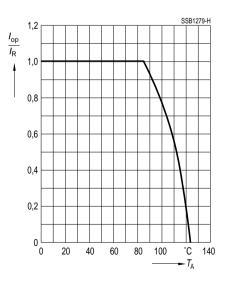
Q factor versus frequency f measured with impedance analyzer HP 4194A



Inductance L versus dc load $I_{\rm DC}$ measured with LCR meter HP 4275A



Current derating I_{op}/I_{R} versus ambient temperature T_{A} (Rated temperature $T_{R} = 40$ °C)





General technical data

Rated inductance L _R	Measured at frequency f_L , with impedance analyzer HP 4194A
Q factor Q _{min}	Measured at frequency $f_{\rm Q}$, with impedance analyzer HP 4194A
Rated current I _N	Maximum permissible dc with an inductance decrease of Δ $L/L_0 \le 10$ % and/or temperature increase of ≤ 40 K at rated temperature $T_R = 85$ °C (see derating curve)
Self resonance frequency $f_{\text{res, min}}$	Measured with network analyzer HP 8753D
DC resistance R _{max}	Measured at 20°C ambient temperature, Measuring current $< I_R$
Climatic category	In accordance with IEC 68- 1 55/125/56 (– 55°C/+ 125°C/56 days damp heat test)
Solderability	(215 ± 3) °C, (3 ± 0.3) s Wetting of soldering area: \geq 90 %
Resistance to soldering heat	In accordance with IEC 68- 2- 20, test Tb 260 °C, 10 s
Permissible PCB bending	2 mm (100 mm long standard PCB)



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